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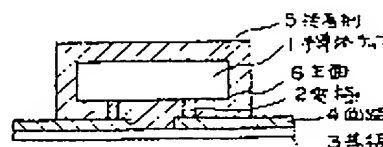
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(54) SEMICONDUCTOR CHIP ATTACHED STRUCTURE

(57)Abstract:

PURPOSE: To obtain a semiconductor chip attached structure effective for shortening the manufacturing processes and for improving reliability of connection by covering whole the surface of the semiconductor chip with the same adhesive.

CONSTITUTION: A wiring board to be connected with electrodes has a circuit 4 formed of copper, aluminum, gold, chromium, tantalum, indium oxide or the like on a substrate 3 of glass, a synthetic resin or a metal. The surface of a semiconductor 1 is totally covered with the same adhesive 5 except contact parts between the surface of the electrodes 2 and the surface of the circuit 4 which are brought into contact with each other by utilizing projections and recesses defined on the surfaces thereof. The adhesive 5 may be any of synthetic resins or low-melting glasses. In order to attach the semiconductor chip 1, the adhesive may be mounted on the semiconductor chip 1 or between the semiconductor chip 1 and the circuit 4 and it is heated and pressurized to be molten and cured. By the pressurizing, the electrodes 2 and the circuit 4 can be connected electrically and the semiconductor chip 1 can be sealed by covering it with an excessive part of the adhesive.



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